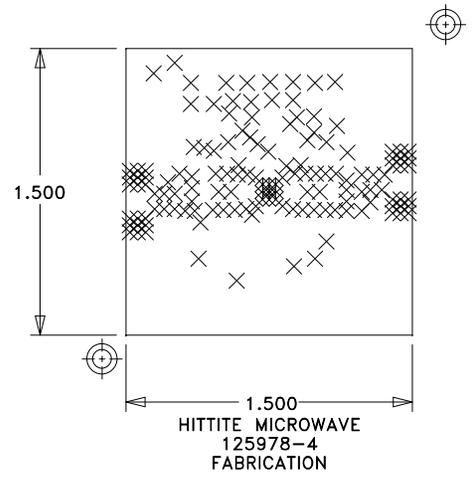
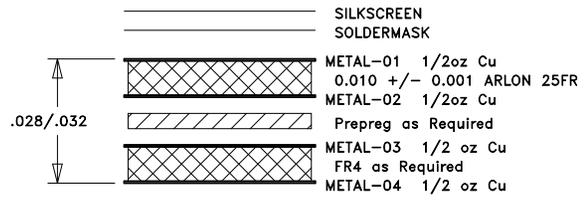


DO NOT SCALE PRINT

REVISION				
ZONE	LTR	DESCRIPTION	DATE	APPROVED
	3	PROVIDE FOR BACKPLATE	11/17/09	G. HARRINGTON
	4	CHANGED TO MULTILAYER	3/19/10	G. HARRINGTON



**NOTES:**  
**UNLESS OTHERWISE SPECIFIED**

1. MATERIAL: MULTILAYER. OVERALL STACKUP AS SHOWN. TYPE ARLON 25FR, HALF OUNCE COPPER BOTH SIDES, TOP SIDE ONLY. FR4 TO BE USED AS FILLER TO MEET CRITICAL OVERALL THICKNESS.
2. FINISH: GOLD PLATE PER ASTM B-488, TYPE III, CODE A, 8 TO 40 MICROINCHES, OVER NICKEL PER QQ-N-290, 100 MICROINCHES MINIMUM.
3. PLATED THRU HOLES: .001" MINIMUM WALL THICKNESS.
4. HOLE SIZES AND POSITIONS PER ARTWORK AND/OR DRILL FILE.
5. ALL HOLES TO BE LOCATED WITHIN  $\pm 0.003$ " OF THE CENTER OF THE PAD OR OTHER TRUE POSITION.
6. FRONT TO BACK REGISTRATION  $\pm 0.003$ " MAX.
7. BOARD WARPAGE:  $< .010$ " PER LINEAR INCH.
8. SILKSCREEN TOP SIDE ONLY WITH WHITE EPOXY INK.
9. TOLERANCE ON PCB ROUTE IS  $\pm 0.005$ ".
10. PLATING THICKNESS  $.002 \pm 0.0005$  FOR METAL-01 AND METAL-02.
11. SOLDERMASK: LPI SOLDERMASK TOP SIDE. COLOR: GREEN REGISTRATION:  $\pm 0.004$  MAX.
12. REMOVE METAL BURRS FROM EDGE OF PCB AFTER PANEL SEPARATION.
13. ARTWORK IS 1:1. VENDOR TO ADJUST FOR ETCH FACTOR.
14. "SIZE" IN DRILL LEGEND IS IN MILS AND REFERS TO FINISHED HOLE SIZE.
15. BOARDS MUST PASS VISUAL INSPECTION PER IPC-A-600 CLASS 2.

**SPECIAL REQUIREMENTS:**

16. CRITICAL LINE WIDTH =  $.016 \pm 0.001$ " ADJUST PROCESS TO ACHIEVE WIDTH.

SIZE	QTY	SYM	PLATED	TOL
10	9	◇	YES	+/-3
14	130	×	YES	+/-3

PROPRIETARY TO HITTITE MICROWAVE CORPORATION

UNLESS OTHERWISE SPECIFIED:		DWN BY:		 <b>HITTITE MICROWAVE CORPORATION</b> 20 Alpha Road Chelmsford, MA 01824			
DIMENSIONS ARE IN INCHES (MM)		MARTIN LYONS 05/08/09					
DRAWING PRACTICES PER MIL-STD-100		ENGINEER:		TITLE <b>PCB, EVAL 50 OHM HMC770LP4B</b>			
TOLERANCES:		SELEN KILINC					
.XX	+/- 0.010			SIZE	CODE ID NO.	DRAWING NO.	REV
.XXX	+/- 0.005			A	1CN88	125978	4
.XXXX	+/- 0.002			SCALE:		WT	SHEET 1 of 1
ANGLES	+/- .5 DEG						